What is claimed is :

1. A composite substance for forming a conductive paste, comprising :

a solvent being compatible with an organic component included in said conductive paste ; and

metal particles wetted by said solvent.

2. The composite substance defined in claim 1, wherein : each of said metal particles is wetted by said solvent.

3. The composite substance defined in claim 1, wherein : said metal particles have an average particle size of 1 μ m or smaller.

4. The composite substance defined in claim 1, wherein : the content of said solvent is 2 to 100 weight units relative to 100 weight units of said metal particles.

5. The composite substance defined in claim 1, wherein : said solvent contains an organic vehicle.

6. A composite substance for forming a conductive paste, comprising :

a solvent being compatible with an organic component included in said conductive paste ; and

metal – compound particles wetted by said solvent.

7. The composite substance defined in claim 6, wherein : each of said metal – compound particles is wetted by said solvent.

8. The composite substance defined in claim 6, wherein : said metal – compound particles have an average particle size of 1 μ m or smaller.

9. The composite substance defined in claim 6, wherein : the content of said solvent is 2 to 100 weight units relative to 100 weight units of said metal – compound particles.

10. The composite substance defined in claim 6, wherein : said solvent contains an organic vehicle.

11. A conductive paste comprising :

an organic binder ;

a composite substance including a solvent being compatible with said organic binder, and metal particles being wetted by said solvent ; and

an organic solvent mixed with said organic binder and said composite substance.

12. The conductive paste defined in claim 11, wherein : each of said metal particles is wetted by said solvent.

13. The conductive paste defined in claim 11, wherein :

said metal particles have an average particle size of 1 μ m or smaller.

14. The conductive paste defined in claim 11, wherein :

the content of said solvent included in said composite substance is 2 to 100 weight units relative to 100 weight units of said metal particles.

15. The conductive paste defined in claim 11, wherein :

said solvent included in said composite substance contains an organic vehicle.

16. A conductive paste comprising :

an organic binder ;

a composite substance including a solvent being compatible with said organic binder, and metal – compound particles being wetted by said solvent ; and

an organic solvent mixed with said organic binder and said composite substance.

17. The conductive paste defined in claim 16, wherein :

each of said metal – compound particles is wetted by said solvent.

18. The conductive paste defined in claim 16, wherein :

said metal – compound particles have an average particle size of 1 μ m or smaller.

19. The conductive paste defined in claim 16, wherein :

the content of said solvent included in said composite substance is 2 to 100 weight units relative to 100 weight units of said metal – compound particles.

20. The conductive paste defined in claim 16, wherein :

said solvent included in said composite substance contains an organic vehicle.

21. An electronic component comprising :

a ceramic base body ; and

at least one electrode supported by said ceramic base body, wherein :

said at least one electrode is formed by using the conductive paste defined in claim 11.

22. An electronic component comprising :

a ceramic base body ; and

at least one electrode supported by said ceramic base body, wherein :

said at least one electrode is formed by using the conductive paste defined in claim 16.

23. A method for manufacturing a composite substance used to form a conductive paste, comprising the step of :

adding a solvent to undried metal particles having been washed with water, said solvent being compatible with an organic

component included in said conductive paste and incompatible with water so that said water is replaced by said solvent.

24. The method defined in claim 23, wherein :

said solvent is added at a rate of 3 to 30 weight units relative to 100 weight units representing the total quantity of said metal particles.

25. The method defined in claim 23, further comprising the step of :

adding a surface active agent together with said solvent, at a rate of 0.05 to 10.0 weight units relative to 100 weight units of the entire quantity of said metal particles.

26. The method defined in claim 25, further comprising the step of :

adding another solvent being compatible with water.

27. The method defined in claim 26, wherein :

said solvent being compatible with water is added at a rate of 0.3 to 30 weight units relative to 100 weight units representing the total quantity of said metal particles.

28. The method defined in claim 26, wherein :

said solvent being compatible with water is acetone.

29. A method for manufacturing a composite substance

used to form a conductive paste, comprising the step of :

adding a solvent to undried metal – compound particles having been washed with water, said solvent being compatible with an organic component included in said conductive paste and incompatible with water so that said water is replaced by said solvent.

30. The method defined in claim 29, wherein :

said solvent is added at a rate of 3 to 30 weight units relative to 100 weight units representing the total quantity of said metal – compound particles.

31. The method defined in claim 29, further comprising the step of :

adding a surface active agent together with said solvent, at a rate of 0.05 to 10.0 weight units relative to 100 weight units of the entire quantity of said metal – compound particles.

32. The method defined in claim 31, further comprising the step of :

adding another solvent being compatible with water.

33. The method defined in claim 32, wherein :

said solvent being compatible with water is added at a rate of 0.3 to 30 weight units relative to 100 weight units representing the total quantity of said metal – compound particles.

34. The method defined in claim 32, wherein :

said solvent being compatible with water is acetone.

35. A method for manufacturing a conductive paste, comprising the step of :

mixing an organic binder and an organic solvent with a composite substance comprising a solvent being compatible with said organic binder, and metal particles wetted by said solvent.

36. The method defined in claim 35, wherein :

said metal particles have an average particle size of 1 μ m or smaller.

37. The method defined in claim 35, wherein :

the content of said solvent included in said composite substance is 2 to 100 weight units relative to 100 weight units of said metal particles.

38. The method defined in claim 35, wherein :

said solvent included in said composite substance contains an organic vehicle.

39. A method for manufacturing a conductive paste, comprising the step of :

mixing an organic binder and an organic solvent with a composite substance comprising a solvent being compatible with said organic binder, and metal – compound particles wetted by

said solvent.

40. The method defined in claim 39, wherein :

said metal – compound particles have an average particle size of 1 μ m or smaller.

41. The method defined in claim 39, wherein :

the content of said solvent included in said composite substance is 2 to 100 weight units relative to 100 weight units of said metal – compound particles.

42. The method defined in claim 39, wherein :

said solvent included in said composite substance contains an organic vehicle.